
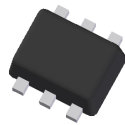


SURFACE MOUNT SCHOTTKY BARRIER DIODE ARRAYS
Features

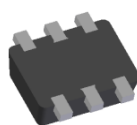
- Low Forward Voltage Drop
- Fast Switching
- Ultra-Small Surface Mount Package
- PN Junction Guard Ring for Transient and ESD Protection
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

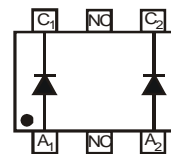
- Case: SOT563, Molded Plastic
- Case Material: Molded Plastic, "Green" Molding Compound.
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe.
Solderable per MIL-STD-202, Method 208 
- Terminals: Lead Bearing Terminal Plating Available
- Weight: 0.003 grams (Approximate)



Top View



Bottom View

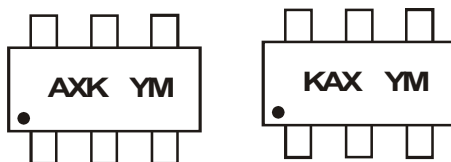


Device Schematic

Ordering Information (Note 4)

Part Number	Case	Packaging
BAT40V-7	SOT563	3,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information


AXK or KAX = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: C = 2015)
 M = Month (ex: 9 = September)

Date Code Key

Year	2004	2005	2006	2007	2008	2009	2010	2015	2016	2017	2018
Code	R	S	T	U	V	W	X	C	D	E	F
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	40	V
Working Peak Reverse Voltage	V_{RWM}		
DC Blocking Voltage	V_R		
Forward Continuous Current (Note 5)	I_F	200	mA
Repetitive Peak Forward Current (Note 5)	I_{FRM}	350	mA
Forward Surge Current (Note 5) @ $t_p = 10\text{ms}$	I_{FSM}	750	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_D	150	mW
Thermal Resistance, Junction to Ambient Air (Note 5)	$R_{\theta JA}$	833	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +125	$^\circ\text{C}$

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	$V_{(BR)R}$	40	—	—	V	$I_R = 100\mu\text{A}$
Forward Voltage	V_F	—	—	330 420 800 1,000	mV	$I_F = 2.0\text{mA}$ $I_F = 15\text{mA}$ $I_F = 100\text{mA}$ $I_F = 200\text{mA}$
Reverse Leakage Current (Note 6)	I_R	—	—	500	nA	$V_R = 25\text{V}$
Total Capacitance	C_T	—	—	10	pF	$V_R = 1.0\text{V}, f = 1.0\text{MHz}$
Reverse Recovery Time	t_{RR}	—	—	5.0	ns	$I_F = 10\text{mA}$ through $I_R = 10\text{mA}$ to $I_R = 1.0\text{mA}, R_L = 100\Omega$

Notes: 5. Device mounted on FR-4 PCB, 1 inch x 1 inch, 2 oz. Copper.
 6. Short duration pulse test used to minimize self-heating effect.

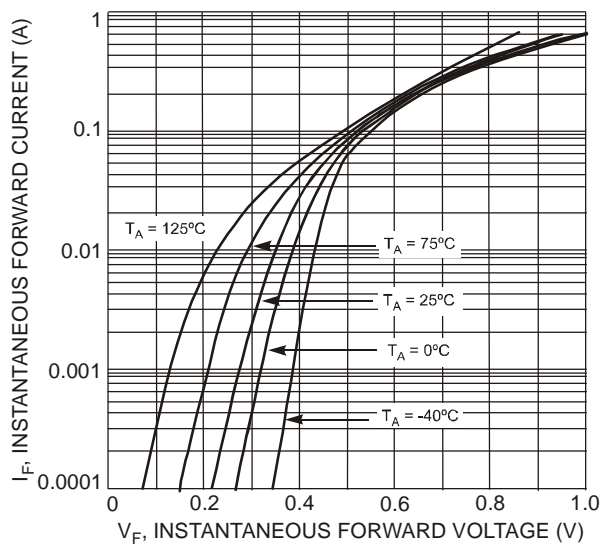


Fig. 1 Typical Forward Characteristics

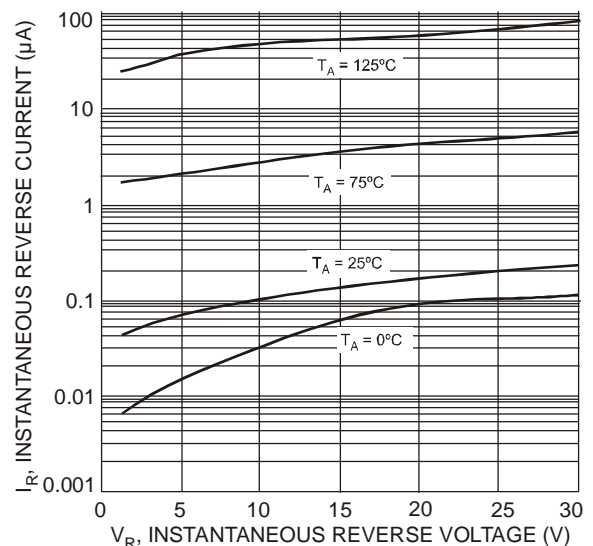
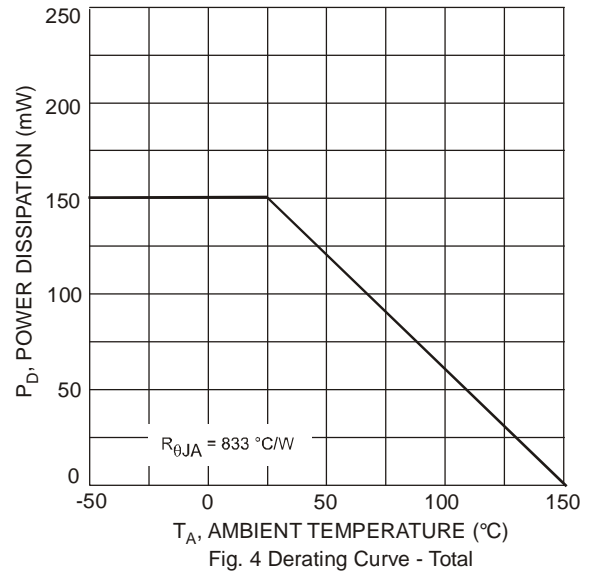
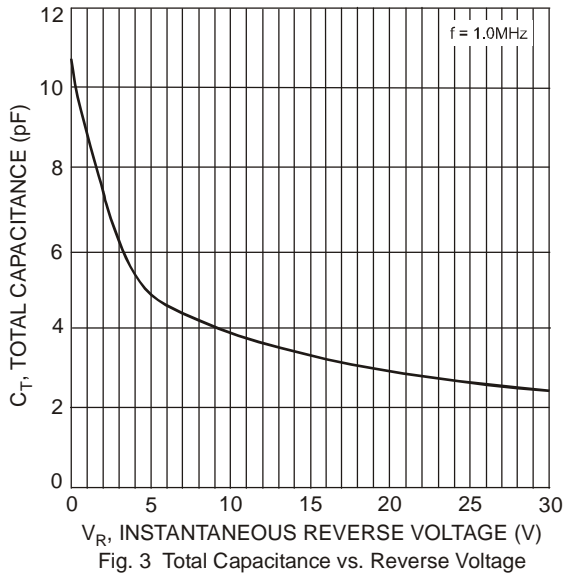
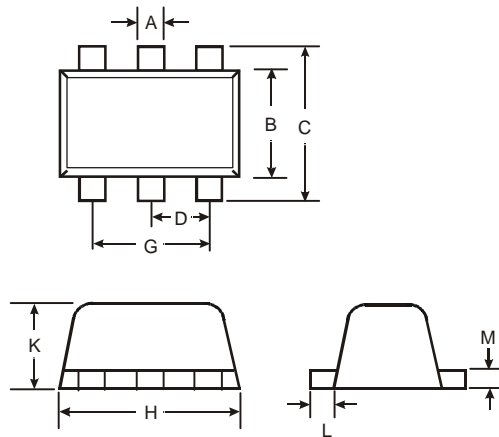


Fig. 2 Typical Reverse Characteristics



Package Outline Dimensions

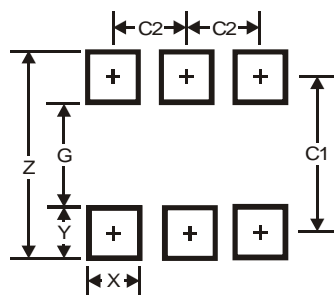
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SOT563			
Dim	Min	Max	Typ
A	0.15	0.30	0.20
B	1.10	1.25	1.20
C	1.55	1.70	1.60
D	-	-	0.50
G	0.90	1.10	1.00
H	1.50	1.70	1.60
K	0.55	0.60	0.60
L	0.10	0.30	0.20
M	0.10	0.18	0.11
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
Z	2.2
G	1.2
X	0.375
Y	0.5
C1	1.7
C2	0.5

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2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

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